



## Material Content Data Sheet



<b>Sales Product Name</b>		BBY 53-05W H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000856196						
<b>Package</b>		PG-SOT323-3-1		<b>Weight*</b>		5.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		10	
	noble metal	gold	7440-57-5	0.006	0.10		1003	
	inorganic material	silicon	7440-21-3	0.051	0.86	0.96	8569	9582
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		440	
	non noble metal	chromium	7440-47-3	0.008	0.13		1321	
	non noble metal	copper	7440-50-8	2.617	43.85	44.03	438443	440292
wire	non noble metal	copper	7440-50-8	0.013	0.22	0.22	2203	2203
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5240	
	plastics	epoxy resin	-	0.672	11.27		112663	
	inorganic material	silicondioxide	60676-86-0	2.424	40.61	52.40	406110	524013
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22233	22233
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1677	1677
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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